



F I G. 1

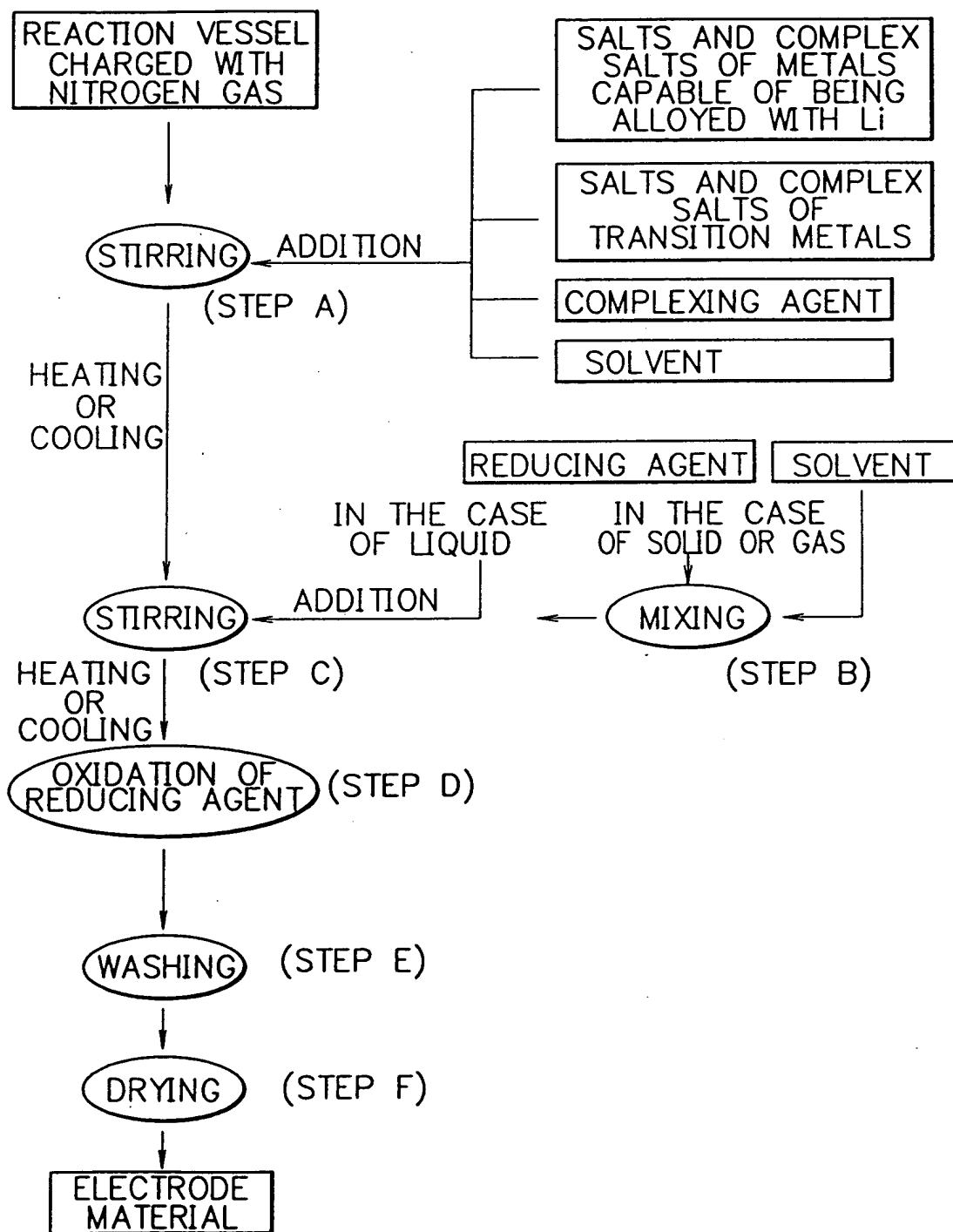




FIG. 2

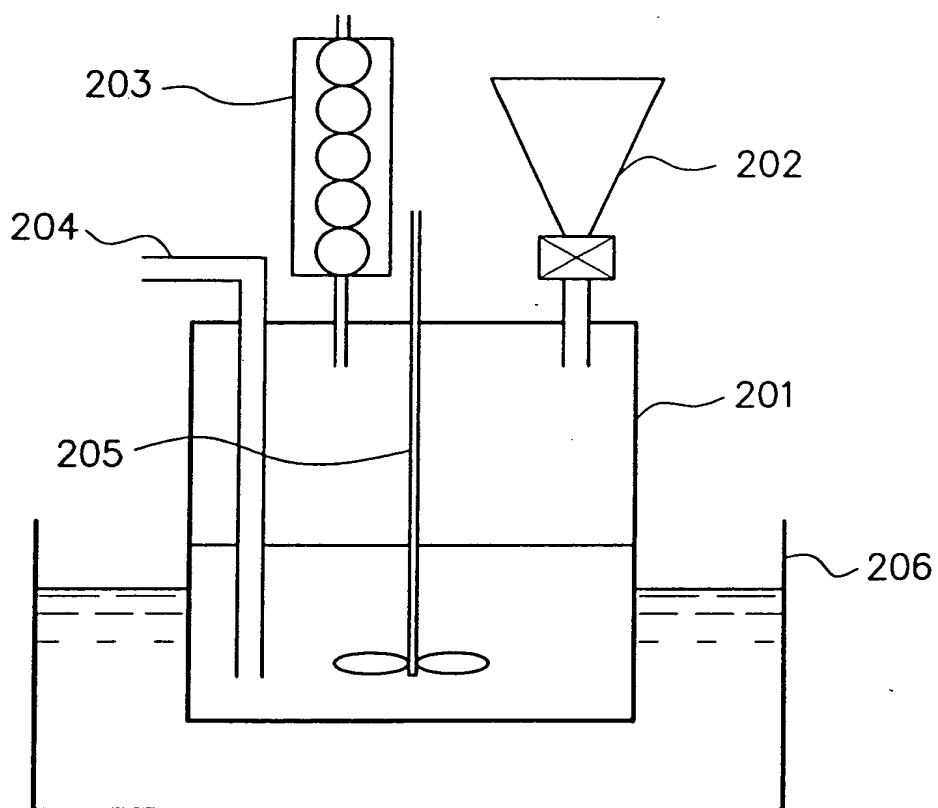
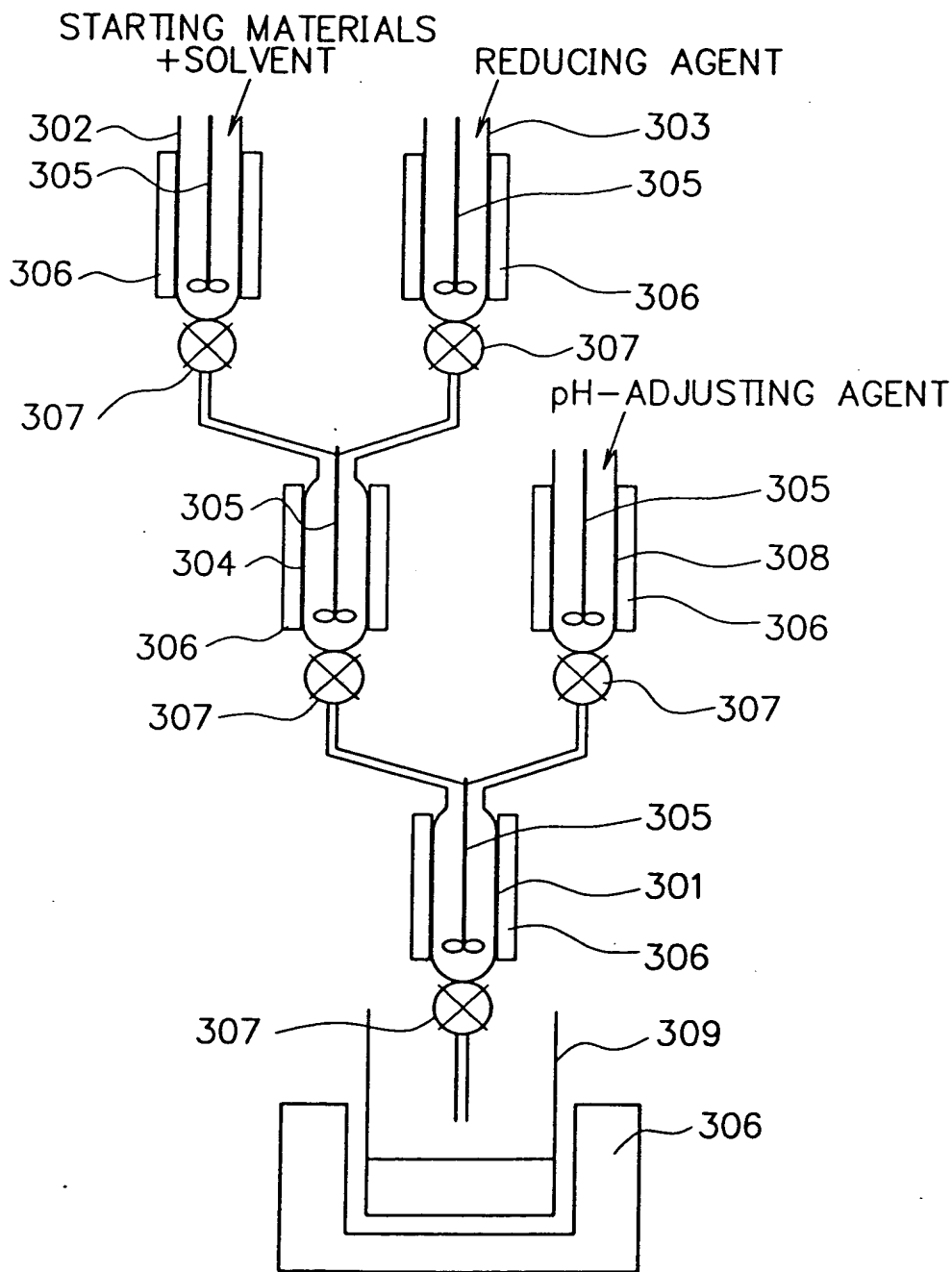
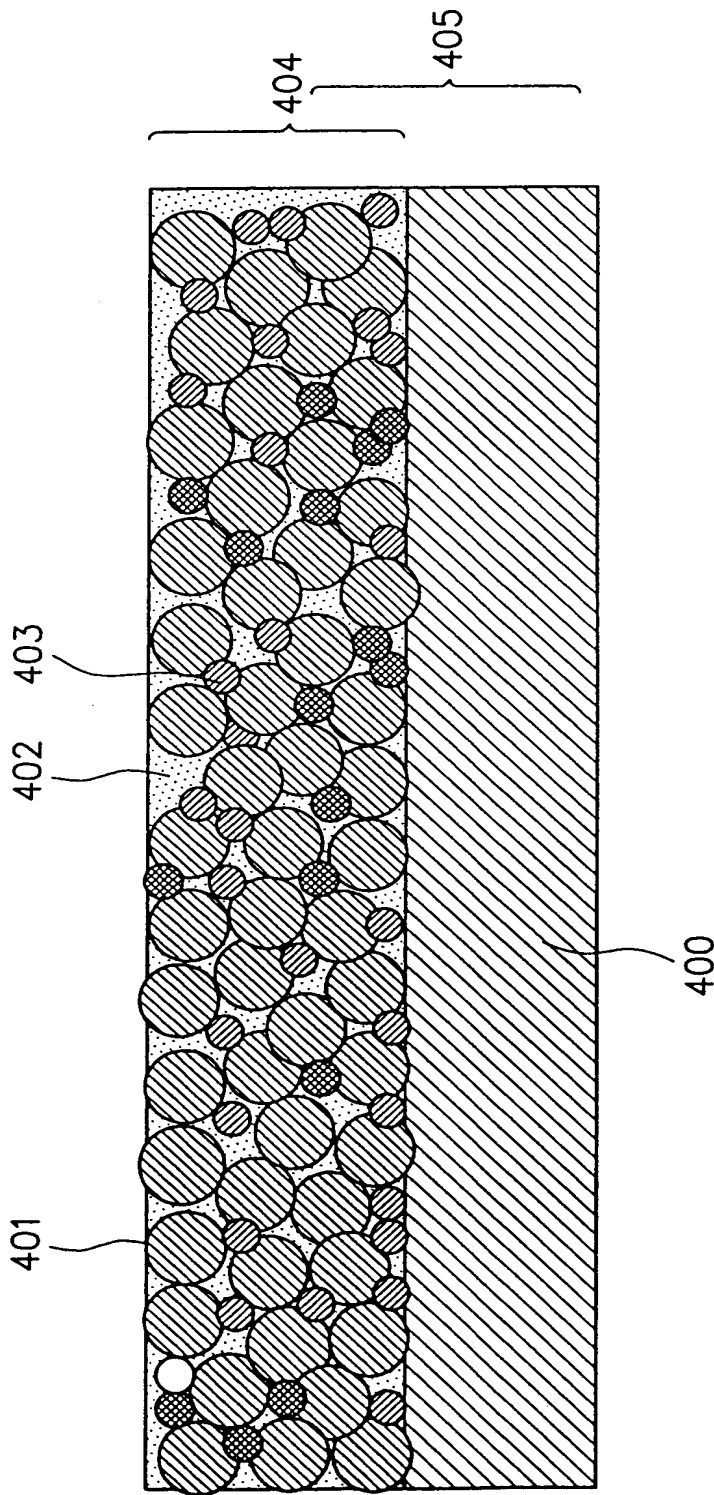


FIG. 3



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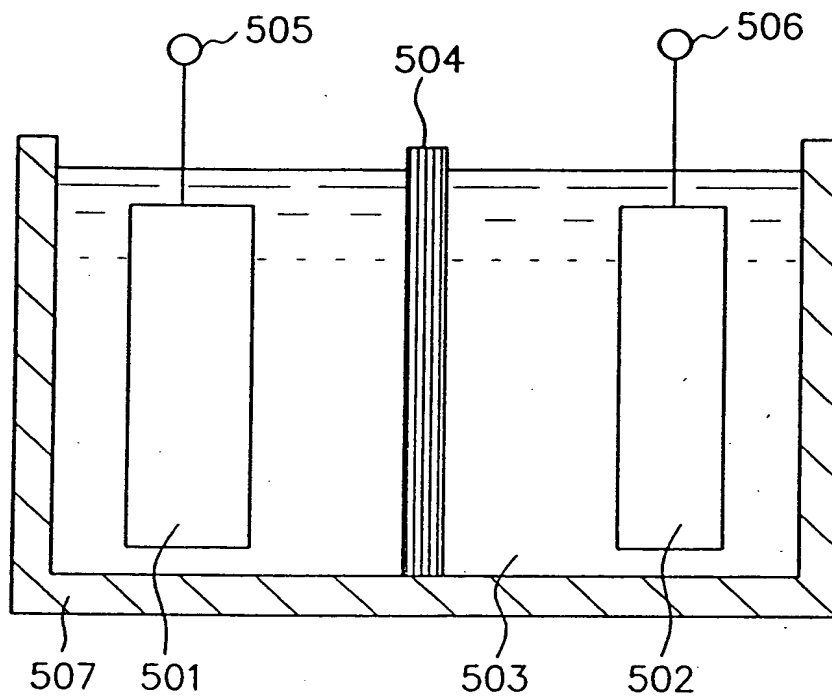
FIG. 4



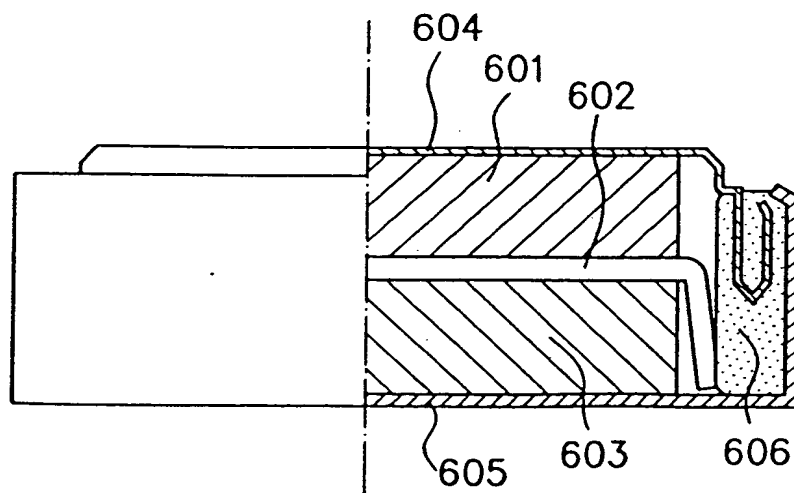


REPLACEMENT SHEET

F I G. 5



F I G. 6

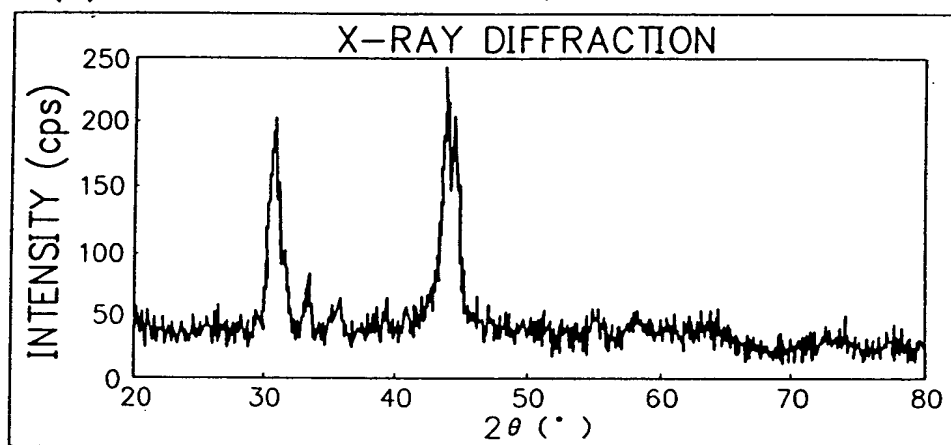


This cross-sectional view illustrates a multi-layered electronic device assembly. The assembly consists of several stacked layers, including a top layer (714), a middle layer (709), and a bottom layer (708). A central component (713) is positioned within the assembly, surrounded by a material (710). The assembly is further defined by layers 711, 703, 706, 705, 707, 702, 701, 704, and 411. The central component (713) is shown with a series of vertical lines, indicating a segmented or multi-layered structure. The layers are labeled with reference numerals 714, 709, 713, 710, 711, 703, 706, 705, 707, 702, 701, 704, 411, 712, 711, and 708.



FIG. 8

(1)



(2)

